



年 程 科 技 股 份 有 限 公 司
TECSTAR TECHNOLOGY CO., LTD.

TB 100505 Z300



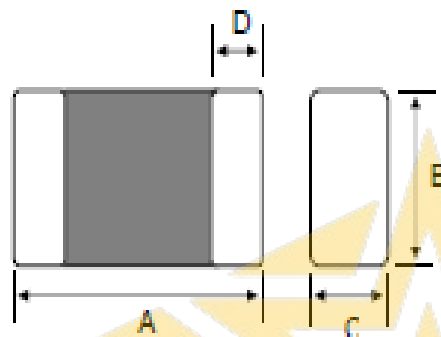
Physical Dimensions : mm (inch)

A = 1.0 ± 0.1 (0.040 \pm 0.004)

B = 0.5 ± 0.1 (0.020 \pm 0.004)

C = 0.5 ± 0.1 (0.020 \pm 0.004)

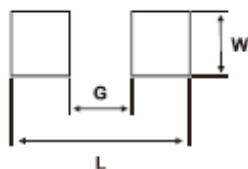
D = 0.25 ± 0.15 (0.010 \pm 0.006)



General Information :

1. Termination Finish is 100% Tin.
2. Components Should be Adequately Preheated Before Soldering.
3. Operating Temperature: -55°C to +125°C
4. Storage Temperature (on Tape & Reel): 40°C MAX. , 70% RH

Land Patterns for Reflow Soldering



| L | W | G |
|-------------|-------------|-------------|
| 2.20(0.086) | 0.70(0.028) | 0.40(0.016) |

Packing Method:

One reel = 10,000 pcs

One Box = 500,000 pcs

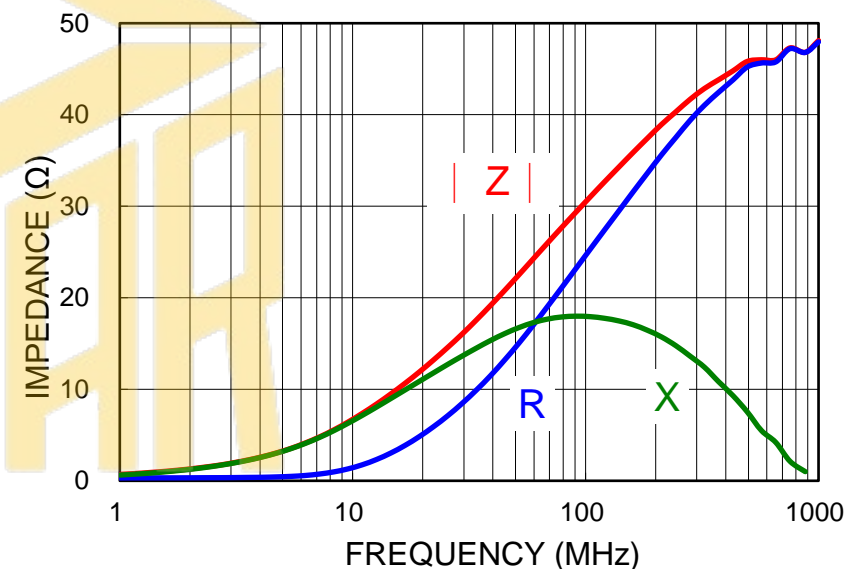
One Box = 8.4 KG

Electrical Characteristics :

| | Value | Unit | Tolerance | Test Condition |
|-----------|-------|----------|------------|----------------|
| Impedance | 30 | Ω | $\pm 25\%$ | 100MHz / 100mV |
| DCR | 0.30 | Ω | Max. | |
| IDC | 500 | mA | Max. | |

Typical Impedance Characteristics : HP 4291B

TB100505Z300



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|------|-------------|------|----|-------------------------------|----------------|--|
| | | | | Multilayer Ferrite Chip Beads | | +886-3-4962286 www.tecstar.com.tw |
| | | | | P/N | TB 100505 Z300 | |
| N000 | Initial | | | Version | N000 | |
| VER. | DESCRIPTION | DATE | BY | | | |
| | | | | | | |